

CROWELL & MORING, L.L.P.  
P.O. Box 14300  
Washington, D.C. 20044-4300  
(202) 624-2500

November 21, 2001

**Box PATENT APPLICATION**

Commissioner for Patents  
Washington, D.C. 20231

Re: New U.S. Patent Appln.  
Our Ref: 381NP/50670

Sir:

Transmitted herewith for filing is the patent application of:

**Hiroyuki KADOTA**

entitled: **ELECTROLYTIC GOLD PLATING METHOD AND APPARATUS  
THEREFOR**


Enclosed are:

1. Specification, including 16 claims (pages 25, plus specification front page).
2. 4 Sheets of X Formal    Informal drawings showing Figs. 1-5.
3. X Declaration and Power of Attorney (**executed**).
4. Assignment of the invention to Hitachi Kyowa Engineering Co., Ltd.
5. The filing fee has been calculated as shown below:

Basic Fee					\$370/740	= \$740.00
Total Claims	<u>30</u>	-	20	=	<u>10</u> x \$9/18	= \$180.00
Independent Claims	<u>9</u>	-	3	=	<u>6</u> x \$42/84	= \$504.00
Multiple Dependent Claim Presented					\$140/280	= \$280.00
Total Filing Fee						<u>\$1,704.00</u>

Two checks in the amount of \$ 1,704.00 for the filing fee and \$ 40.00 for the assignment recording fee are enclosed. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Deposit Account No. 05-1323 (Docket #381NP/50670). A duplicate copy of this sheet is enclosed.

Respectfully submitted,

  
Warren A. Zitlau  
Registration No. 39,085

James F. McKeown  
Registration No. 25,406

JFM:WAZ:vca



23911

PATENT TRADEMARK OFFICE

jc821 U.S. PTO  
09/989469  
11/21/01